3D Packaging and Integration Global Technical Committee

Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Winter Meeting 2024

January 26, 2024, 15:00-17:00[JST]

SEMI Japan, Tokyo Japan/ Official Virtual TC Chapter Meeting (Hybrid)

TC Chapter Announcements

Next TC Chapter Meeting

Thursday, May 14, 2024 14:00-16:00

OVTCCM

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Kazunori Kato (AiT), Masahiro Tsuriya (iNEMI), Haruo Shimamoto (AIST)
SEMI Staff: Mami Nakajo

Company	*Last*	*First*	*Company*	*Last*	*First*
AIST	Shimamoto	Haruo	Nagase	Takahashi	Atsushi
AiT	Kato	Kazunori	Shin-Etsu Polymer Co., Ltd.	Odashima	Satoshi
iNEMI	Tsuriya	Masahiro	Self	Takahashi	Mark
DISCO Corporation	Gonsui	Shinobu	Yokohama National University	Inoue	Fumihiro
SCREEN Semiconductor Solutions Co., Ltd.	Matsumoto	Toshiki	*Yokohama National University*	*Sano*	*Marie*
KOKUSAI ELECTRIC CORPORATION	*Matsuda*	*Mitsuhiro*	SEMI Japan	Nakajo	Mami
Hitachi High-Tech	*Yoshino*	*Eiji*	SEMI Japan	Osawa	Naoko

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
Wafer Bond Strength Measurement by Double-cantilever Beam TF		Fumihiro Inoue (YNU)
Wafer Bond Strength Measurement by Double-cantilever Beam TF		Marie Sano (YNU)

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
	Wafer Bond Strength Measurement by Double-cantilever Beam TF

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
Panel Level Packaging (PLP) Glass Carrier Task Force	Disband

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
None			

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
None			

Table 10 SNARF(s) Abolished

#	*TF*	*Title*
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	*Title*
SEMI G83-0619	Specification for Bar Code Marking of Product Packages
SEMI G29-0519	Test Method for Trace Contaminants in Molding Compounds
SEMI G55-0519	Test Method for Measurement of Silver Plating Brightness
SEMI G43-0519	Test Method for Junction-to-Case Thermal Resistance Measurements of Molded Plastic Packages

Table 12 New Action Items

Item #	*Assigned to*	*Details*
20240126-01	SEMI Staff	to prepare SNARFs for Reapproval documents by next TC Meeting
20240126-02	SEMI Staff	to inform the ballot template to the TF leader

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
20230621-01	SEMI Staff	To submit the ballot review sheets to the A&R

1 Welcome, Reminders, and Introductions

Masahiro Tsuriya (iNEMI)called the meeting to order at 15:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 1.2_Required Element Nov 2022_E+J (new template),

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Kato Kazunori (AiT)
By / 2nd:	Haruo Shimamoto (AIST-National Institute of Advanced Industrial and Technology)
Discussion:	None
Vote:	10 in favor and 0 opposed. Motion passed.

Attachment: 2_20230905_3DPI-Japan_MeetingMinutes_Draft+mt

3 Liaison Reports

3.1 *3D Packaging & Integration North America TC Chapter*

Mami Nakajo (SEMI Japan) reported on the 3D Packaging & Integration North America TC Chapter activity status based on the report as attached.:

Attachment: 3.1_NA 3DP&I Liaison Report Nov2023 v1,

3.2 *3D Packaging & Integration Taiwan TC Chapter*

Mami Nakajo (SEMI Japan) reported on the 3D Packaging & Integration Taiwan TC Chapter activity status based on the report as attached.:

Attachment: 3.2_3D P&I TW Liaison Report_20220902_v1,

4 SEMI Staff Report

Mami Nakajo (SEMI) explained the SEMI Staff Report based on the report as attached.:

Attachment: 4_Staff Report Dec 2023 HK_N_AY_20231220,

Presiding chair was changed from Masahiro Tsuriya (iNEMI) to Kato Kazunori (AiT)

5 Ballot Review

None

6 Subcommittee and Task Force Reports

6.1 GCS Report

- None

6.2 *3D Packaging & Integration 5 Year Review Task Force >*

Masahiro Tsuriya (iNEMI) reported on the 3D Packaging & Integration 5 Year Review Task Force status as attached.

Action Item 20240126-01: (SEMI Staff) to prepare SNARFs for Reapproval documents by next TC Meeting

Attachment: 6.2_TF Report - 5yrs Review TF v2024_1,

6.3 *3DS IC Bonded Layer Inspection Metrology Task Force*

Haruo Shimamoto (AIST) reported on the 3DS IC Bonded Layer Inspection Metrology Task Force. The TF is currently working on the possibility of using alignment mark to separate the boundary plane where the voids are existing.

Action Item 20240126-02: (SEMI Staff) to inform the ballot template to the TF leader

Attachment: 6.3_ActivitiesReport_3DSIC-InspectionTF_20240126_Submit ver2,

6.4 *Panel Level Packaging (PLP) Glass Carrier Task Force*

Mark Takahashi (SELF) made a proposal for disbandment of this TF.

Motion:	Mark Takahashi (SELF)
By / 2nd:	Haruo Shimamoto (AIST-National Institute of Advanced Industrial and Technology)
Discussion:	Haruo Shimamoto (AIST) said that glass carrier standard will be available for glass core substrate manufacturing. So we need to keep watching about the development of glass core substrate. Kato Kazunori (AiT) asked if there has been any discussion regarding packaging. He made a comment that if the discussion has been settled to some extent and standardization is necessary, please support our activity. ~~Haruo Shimamoto (AIST) asked that if Takahashi-san can connect the decisions made by the carriers to the glass core.~~
Vote:	10 in favor and 0 opposed. Motion passed.

6.5 *Steering Working Group*

Masahiro Tsuriya (iNEMI) reported on the 3D Packaging & Integration 5 Year Review Task Force status as attached.

Attachment: 6.5_TF Report - Steering WG v2024_1,

Mami Nakajo (SEMI Japan) reported for the Workshop organized by Steering Working Group to be held at SEMICON Japan as attached and thanked for their support.

Attachment: 6.5_2023_Steering WG Workshop_開催報告,

7 Old Business

7.1 *Project Period Review-*

None

7.2 5 Year Review Check

Please refer to 6.2

8 New Business

8.1 Proposal of New Activity

Fumihiro Innoue(Yokohama National University) made a proposal of new TFOF.

Motion:	Fumihiro Innoue(Yokohama National University)
By / 2nd:	Haruo Shimamoto (AIST-National Institute of Advanced Industrial and Technology)
Discussion:	Kato Kazunori (AiT) gave an advice that another leader from the companies who will join the TF members in the future should be recruited in order to better carry out this new activity and is willing to support for the activity.
Vote:	9 in favor and 0 opposed. Motion passed.

Attachment: TFOF_Feb2020 v4 (6)_Bondstrength_v20240124_R2.0

9 Action Item Review

9.1 Open Action Items

Item #	*Assigned to*	*Details*
20230905-01	SEMI Staff	To submit the ballot review sheets to the A&R> Closed

9.2 New Action Items

Item #	*Assigned to*	*Details*
20240126-01	SEMI Staff	to prepare SNARFs for Reapproval documents by next TC Meeting
20240126-02	SEMI Staff	

10 Next Meeting and Adjournment

The next meeting is scheduled for Thursday, May 23,2024,14:00-16:00 [JST] WEB Only @ OVTCCM

See http://www.semi.org/standards-events for the current list of events.

Adjournment: [16:30]>.

Respectfully submitted by:

Mami Nakajo

Coordinator

SEMI Japan

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Email: mnakajo@semi.org

Minutes tentatively approved by:

Kazunori Kato (AiT), Co-chair	February 15 ,2024
Masahiro Tsuriya (iNEMI), Co-chair	February 19 ,2024
Haruo Shimamoto(AIST), Co-chair	February 18 ,2024

Table 14 Index of Available Attachments#1

Title	*Title*
1.2_Required Element Nov 2022_E+J (new template)	6.3_ActivitiesReport_3DSIC-InspectionTF_20240126_Submit ver2
2_20230905_3DPI-Japan_MeetingMinutes_Draft+mt	6.5_2023_Steering WG Workshop_開催報告
3.1_NA 3DP&I Liaison Report Nov2023 v1	6.5_TF Report - Steering WG v2024_1
3.2_3D P&I TW Liaison Report_20220902_v1	TFOF_Feb2020 v4 (6)_Bondstrength_v20240124_R2.0
4_Staff Report Dec 2023 HK_N_AY_20231220	
6.2_TF Report - 5yrs Review TF v2024_1	

Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.